

Description

The TN71B series is a set of three-terminal low power high voltage regulators implemented in CMOS technology. They allow input voltages as high as 30V. They are available with several fixed output voltages ranging from 2.8V to 9.0V. Because of the low power dissipation, TN71B series are widely used in a variety of equipment such as audio device, video device, communication device and so on.

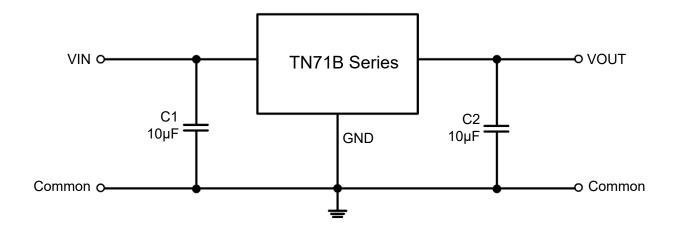
Features

- High Input Voltage Rating: Up to 30V
- Maximum Output Current: 100mA
- Standard Fixed Output Voltage Options: 2.8V,3V,3.3V,3.6V,4V,4.4V,5V and 9V
- Low Quiescent Current: 1.5uA
- PSRR=dB@1KHz
- Low Dropout : 100mV(Max.) @ 1mA
- Low Output Voltage Accuracy: ±2%
- Low Power Consumption
- Low Temperature Coefficient
- Available Packages: SOT-23, SOT-23-3 and SOT-89

Applications

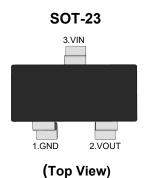
- Battery-Powered Equipment
- Communication Equipment
- Audio/Video Equipment

Typical Application Circuit

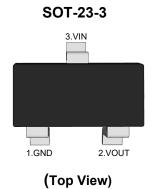




Pin Distribution



SOT-89		
(2.VIN	
1.GND	2.VIN	3.VOUT
(Top View)		



Functional Pin Description

Pin Name	Pin Function
GND	Ground
VOUT	Output Voltage
VIN	Power Input Voltage

Ordering Information

Package Type SA : SOT-23 SC : SOT-23-3 SQ : SOT-89 Output Voltage 28 : 2.8V 30 : 3.0V 33 : 3.3V 36 : 3.6V 40 : 4.0V 44 : 4.4V 50 : 5.0V 90 : 9.0V Output current tap K: 100mA



TN71B Series Low Dropout Regulators

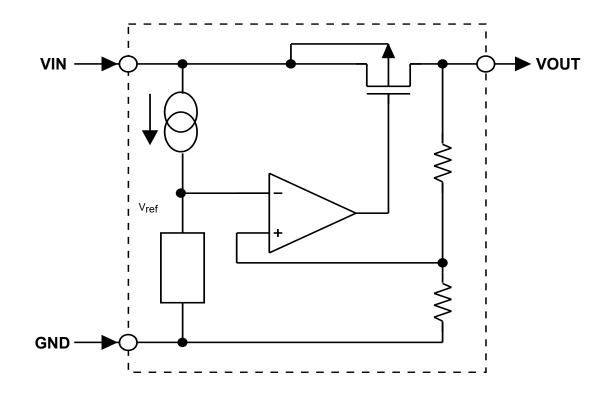
Orderable Device	Package	Reel (inch)	Package Qty (PCS)	Eco Plan ^{Note}	MSL Level	Marking Code
TN71BK28SA						
TN71BK30SA						
TN71BK33SA						
TN71BK36SA	SOT-23	7	3000	RoHS & Green	MSL1	71XX
TN71BK40SA	301-23	/	3000	KUNS & Gleen		
TN71BK44SA						XX:Output Voltage
TN71BK50SA						e.g. 30:3.0V
TN71BK90SA						
TN71BK28SQ						
TN71BK30SQ						
TN71BK33SQ	-					
TN71BK36SQ	SOT-89	7/13	1000/3000	RoHS & Green	MSL1	71XX
TN71BK40SQ	301-69	7/13	1000/3000	KUNS & Gleen		
TN71BK44SQ						XX:Output Voltage
TN71BK50SQ						e.g. 30:3.0V
TN71BK90SQ						
TN71BK28SC						
TN71BK30SC						
TN71BK33SC						
TN71BK36SC	SOT-23-3	7	3000	RoHS & Green	MSL3	71XXC
TN71BK40SC	301-23-3		3000	KUND & Green	IVIƏLƏ	
TN71BK44SC						
TN71BK50SC						XX:Output Voltage e.g. 30:3.0V
TN71BK90SC						

Note:

RoHS: PJ defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Green: PJ defines "Green" to mean Halogen-Free and Antimony-Free.



Function Block Diagram





Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter		Value	Unit
Supply Voltage		-0.3 ~ +30	V
	SOT-23	200	mW
Power Dissipation	SOT-23-3	400	mW
	SOT-89	600	mW
	SOT-23	330	°C/W
Thermal Resistance, Junction-to-Ambient	SOT-23-3	380	°C/W
	SOT-89	180	°C/W
Operating Ambient Temperature		-40 ~ +85	°C
Storage temperature range		-40 ~ +125	°C
ESD Voltage	HBM	2	KV

Note: 1. Exceed these limits to damage to the device, exposure to absolute maximum rating conditions may affect the reliability of the chip.

Recommended Operating Conditions

Parameter	Value	Unit
Supply Voltage	24	V
Maximum Output Current	100	mA
Operating Ambient Temperature	-40 ~ +85	°C



Electrical Characteristics

(V_{IN}=V_{OUT}+2, C_{IN}=10 μ F, C_{OUT}=10 μ F, T_A=25°C , unless otherwise noted.)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Input Voltage	VIN				24	V
Output Voltage Accuracy	ΔVουτ		-2		+2	%
Output Current	Ι _{Ουτ}	V _{IN} =V _{OUT} +2V	50			mA
Quiescent Current	lq	I _{OUT} =0mA		1.5	3.0	μA
Development V / In Note1		2.8V≤V _{OUT} ≤3.0V, ∆V _{OUT} =2%, I _{OUT} =1mA		30	100	mV
Dropout Voltage ^{Note1}	VDROP	3.0V <v<sub>OUT≤9.0V, ∆Vouт=2%, Ioυт=1mA</v<sub>		25	55	mV
Line Regulation	ΔV_{LINE}	V _{IN} =V _{OUT} +1V to 24V,I _{OUT} =1mA			0.2	%/V
Load Regulation	ΔV_{LOAD}	V _{IN} =V _{OUT} +2V,1mA≤I _{OUT} ≤50mA		25	60	mV
Short Current	I _{SHORT}	V _{OUT} =0V		130		mA
Limit Current	ILIMIT	V _{IN} =V _{OUT} + 2V			360	mA
Power Supply Rejection Ratio	PSRR	Vout=3.3V,Iout=50mA, f=1KHz		55		dB
Temperature Coefficient	$\frac{\Delta V_{OUT}}{\Delta T_A \times \Delta V_{OUT}}$	V _{IN} =V _{OUT} +2V,I _{OUT} =1mA, -40°C≤T _A ≤85°C		100		ppm/°C

Note 1. The dropout voltage is defined as $V_{IN} - V_{OUT}$, when V_{OUT} is 98% of the normal value of V_{OUT} .



Functional Description

Input Capacitor

A 10µF ceramic capacitor is recommended to connect between VIN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both VIN and GND.

Output Capacitor

An output capacitor is required for the stability of the LDO. The recommended minimum output capacitance is 10µF, ceramic capacitor is recommended, and temperature characteristics are X7R or X5R. Higher capacitance values help to improve load/line transient response. The output capacitance may be increased to keep low undershoot/overshoot. Place output capacitor as close as possible to VOUT and GND pins.

Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula : $P_{D(MAX)} = (T_{J(MAX)} - T_A) / R_{\theta JA}$

Where $T_{J(MAX)}$ is the maximum operation junction temperature 125 °C, T_A is the ambient temperature and the $R_{\theta JA}$ is the junction to ambient thermal resistance.

The power dissipation definition in device is:

 $\mathsf{P}_\mathsf{D} = (\mathsf{V}_\mathsf{IN} - \mathsf{V}_\mathsf{OUT}) \times \mathsf{I}_\mathsf{OUT} + \mathsf{V}_\mathsf{IN} \times \mathsf{I}_\mathsf{Q}$

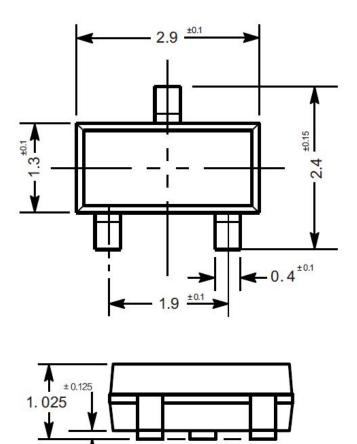
Layout Consideration

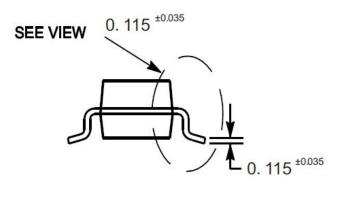
By placing input and output capacitors on the same side of the PCB as the LDO, and placing them as close as is practical to the package can achieve the best performance. The ground connections for input and output capacitors must be back to the TN71B Series ground pin using as wide and as short of a copper trace as is practical.Connections using long trace lengths, narrow trace widths, and connections through via must be avoided. These add parasitic inductances and resistance that results in worse performance especially during transient conditions.

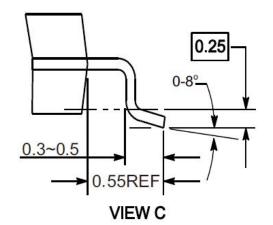


Package Outline

SOT-23 Dimensions in mm





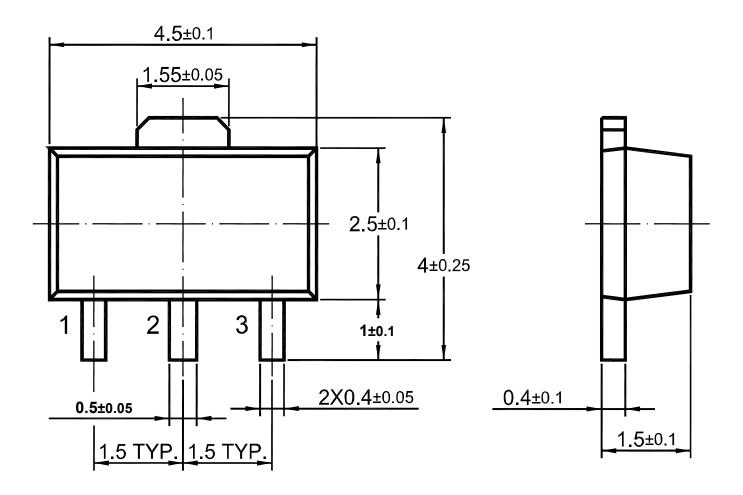


0.05



Package Outline

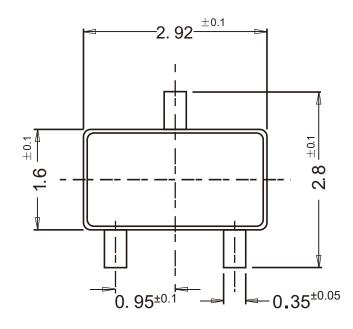
SOT-89 Dimensions in mm

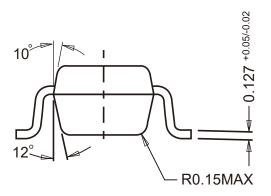


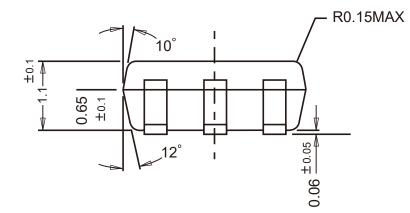


Package Outline

SOT-23-3 Dimensions in mm



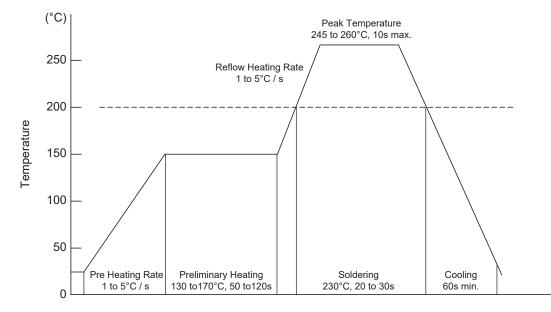






Conditions of Soldering and Storage

Recommended condition of reflow soldering



Recommended peak temperature is over 245°C. If peak temperature is below 245°C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)
- Conditions of hand soldering
- Temperature: 300°C
- Time: 3s max.
- Times: one time

• Storage conditions

• Temperature

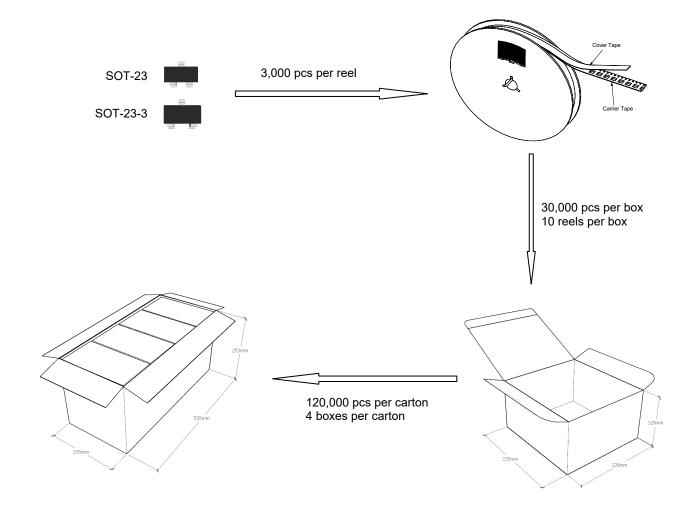
5 to 40°C

- Humidity
 30 to 80% RH
- Recommended period One year after manufacturing

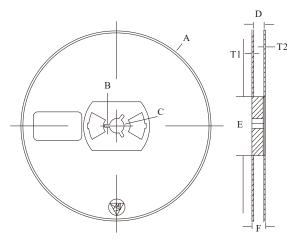


Package Specifications (SOT-23/SOT-23-3)

• The method of packaging



Embossed tape and reel data

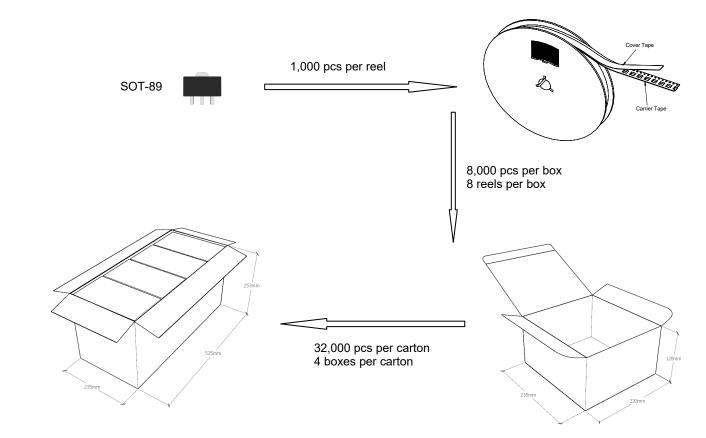


Symbol	Value (unit: mm)
A	Ø 177.8±1
В	2.7±0.2
С	Ø 13.5±0.2
E	Ø 54.5±0.2
F	12.3±0.3
D	9.6+2/-0.3
T1	1.0±0.2
T2	1.2±0.2

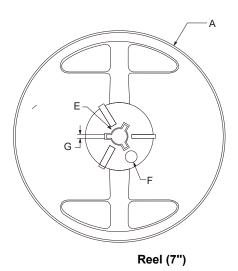


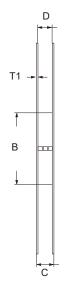
Package Specifications (SOT-89)

• The method of packaging (1,000PCS/Reel&7inches)



• Embossed tape and reel data



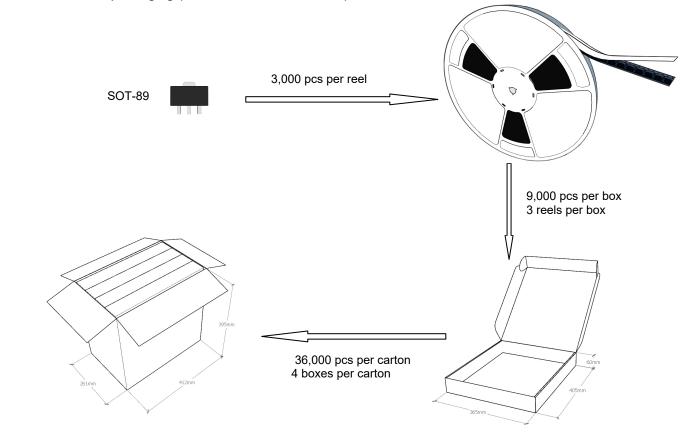


symbol	Value(unit:mm)
A	Φ179±1
В	60.5±0.2
С	15.3±0.3
D	12.5~13.7
E	Ф13.5±0.2
F	Ф10.0±0.2
G	2.7±0.2
T1	1.0±0.2

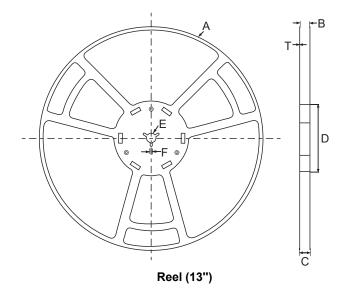


Package Specifications (SOT-89)

• The method of packaging (3,000PCS/Reel&13inches)



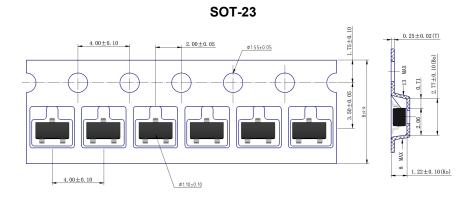
Embossed reel data



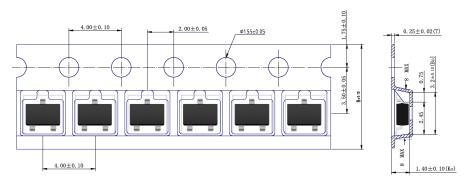
symbol	Value(unit:mm)
A	φ 330±1
В	12.7±0.5
С	16.5±0.3
D	φ99.5±0.5
E	φ 13.6±0.3
F	2.8±0.3
Т	1.9±0.2



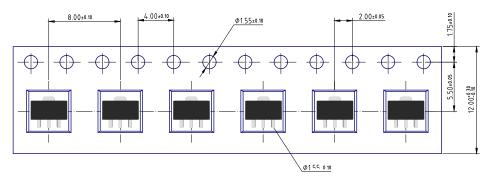
Embossed tape data



SOT-23-3



SOT-89





Contact Information

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For additional information, please contact your local Sales Representative.

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Product Specification Statement

The product specification aims to provide users with a reference regarding various product parameters, performance, and usage. It presents certain aspects of the product's performance in graphical form and is intended solely for users to select product and make product comparisons, enabling users to better understand and evaluate the characteristics and advantages of the product. It does not constitute any commitment, warranty, or guarantee.

The product parameters described in the product specification are numerical values, characteristics, and functions obtained through actual testing or theoretical calculations of the product in an independent or ideal state. Due to the complexity of product applications and variations in test conditions and equipment, there may be slight fluctuations in parameter test values. TANI shall not guarantee that the actual performance of the product when installed in the customer's system or equipment will be entirely consistent with the product specification, especially concerning dynamic parameters. It is recommended that users consult with professionals for product selection and system design. Users should also thoroughly validate and assess whether the actual parameters and performance when installed in their respective systems or equipment meet their requirements or expectations. Additionally, users should exercise caution in verifying product compatibility issues, and TANI assumes no responsibility for the application of the product. TANI strives to provide accurate and up -to- date information to the best of our ability. However, due to technical, human, or other reasons, TANI cannot guarantee that the information provided in the product specifications.

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The design of the product is intended to meet civilian needs and is not guaranteed for use in harsh environments or precision equipment. It is not recommended for use in systems or equipment such as medical devices, aircraft, nuclear power, and similar systems, where failures in these systems or equipment could reasonably be expected to result in personal injury. TANI shall assume no responsibility for any consequences resulting from such usage.

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